

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Tae Hee PARK</td> <td>07/16/2012</td> </tr> <tr> <td>Kyu Tae LEE</td> <td>07/16/2012</td> </tr> <tr> <td>Jung Suk LEE</td> <td>07/16/2012</td> </tr> </tbody> </table>		Name	Execution Date	Tae Hee PARK	07/16/2012	Kyu Tae LEE	07/16/2012	Jung Suk LEE	07/16/2012
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Tae Hee PARK	07/16/2012								
Kyu Tae LEE	07/16/2012								
Jung Suk LEE	07/16/2012								
RECEIVING PARTY DATA									
Name:	NEOENBIZ								
Street Address:	A-1306, Bucheon Dawoo Techno Park								
Internal Address:	Dodang-dong 187-7, Wonmi-gu, Bucheon-si								
City:	Gyeonggi-Do								
State/Country:	KOREA, REPUBLIC OF								
Postal Code:	420-806								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13578424</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13578424				
Property Type	Number								
Application Number:	13578424								
CORRESPONDENCE DATA									
Fax Number:	3034998089								
Phone:	3034998080								
Email:	rfriedland@greenleesullivan.com								
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>									
Correspondent Name:	Ronald Friedland								
Address Line 1:	4875 Pearl East Circle, Suite 200								
Address Line 4:	Boulder, COLORADO 80301								
ATTORNEY DOCKET NUMBER:	83-12								
NAME OF SUBMITTER:	GARY B. CHAPMAN								
Total Attachments: 2 source=83-12_US_exd_assignment#page1.tif source=83-12_US_exd_assignment#page2.tif									

CH \$40.00 13578424

ASSIGNMENT

WHEREAS, I, **PARK, Tae Hee**, residing at 4F Rm.402, Banghak-dong 690-32, Dobong-gu, Seoul 132-851 Republic of Korea; **LEE, Kyu Tae**, residing at A-1306, Bucheon Daewoo Techno Park, Dodang-dong 187-7, Wonmi-gu, Bucheon-si, Gyeonggi-Do 420-806 Republic of Korea and **LEE, Jung Suk** residing at 103-1805, Geongeon e-Pyeonhansesang Apt., Geongeon-dong 987, Sangnok-gu, Ansan-si, Gyeonggi-Do 426-707 Republic of Korea (each herein called "ASSIGNOR"), am an inventor of the invention entitled

NANO-DIAMOND DISPERSION SOLUTION AND METHOD FOR PREPARING SAME

, for which I have executed an application for a Patent of the United States, filed August 10, 2012, Serial No. 13/578,424;

AND WHEREAS, **NEOENBIZ** (herein called "ASSIGNEE"), an entity organized and existing under the laws of the State of Rep. of Korea, having a principal place of business at A-1306, Bucheon Dawoo Techno Park, Dodang-dong 187-7, Wonmi-gu, Bucheon-si, Gyeonggi-Do 420-806 Republic of Korea desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of my contractual and other legal obligations, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, a said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said United States Application and all divisions, renewals, continuations and subsequent applications thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States; together with the right to file such applications and the right to claim for the same the priority of said patent applications listed herein and applications thereof and therefrom under The International Union for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application and applications thereof and therefrom is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY authorize the above-mentioned ASSIGNEE or its legal representative to insert in this instrument the filing date and serial number of said application(s) or any other information that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document;

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all continuing and subsequent applications, including divisional, reissue and foreign applications, make all rightful oaths, and generally cooperate and do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain, maintain, and enforce proper protection for said invention in any and all countries;

IN TESTIMONY WHEREOF, I hereunto set my hand and seal (if applicable) the day and year set opposite my signature.

2012.07.16
Date



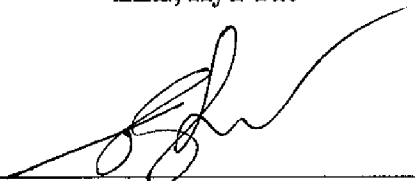
PARK, Tae Hee

2012.07.16
Date



LEE, Kyu Tae

2012.07.16
Date



LEE, Jung Suk

Additional Assignors on additional sheets: No